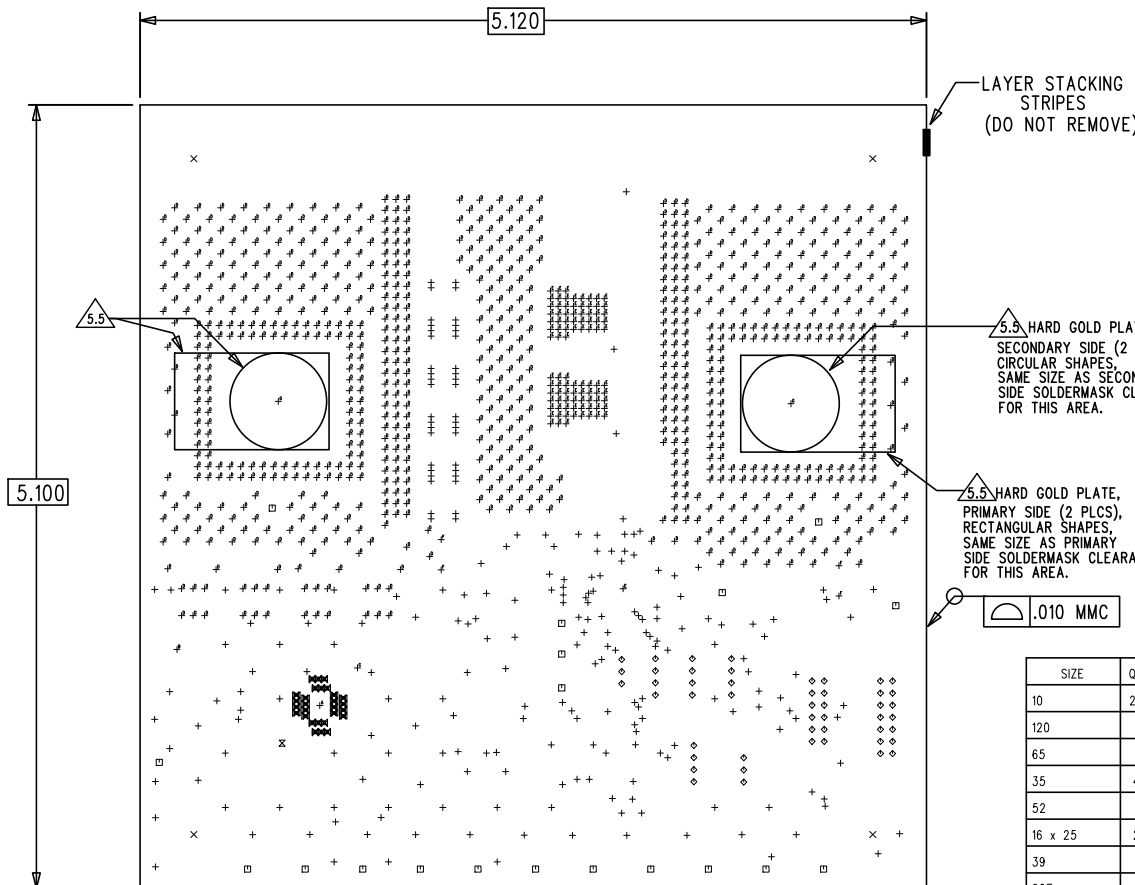


NOTES: UNLESS OTHERWISE SPECIFIED

REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
			DATE

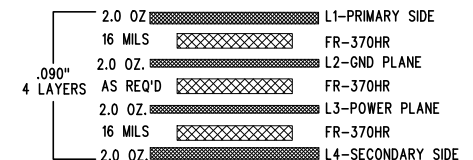
- FAB PER IPC-A-600.
- MATERIAL: -LEAD FREE ASSEMBLY COMPLIANT, FR-370HR OR EQUIVALENT.
-FINISHED COPPER TO COPPER THICKNESS SHALL BE 0.090 IN. +/- 10%
-TOTAL OF 4 LAYERS WITH FINISHED COPPER THICKNESS 2.0 OZ. ALL LAYERS.
-STACKUP AS PER FIG.1, "LAYER STRUCTURE".
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
- SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
- DRILLING:
 - DRILL HOLES PER SCHEDULE, HOLE PLATING 1 OZ THICK MINIMUM.
 - ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
 - HOLE LOCATION TOLERANCES AS FOLLOWS:
 - 3 MILS DIAMETER TRUE POSITION TOLERANCE FOR ALL HOLES 68 MILS DIAMETER OR LESS.
 - 6 MILS DIAMETER TRUE POSITION TOLERANCE FOR ALL OTHER HOLES.
 - ALL 12 MIL DIAMETER VIAS, QTY 107, SHALL BE IPC 4761 TYPE VII FILLED AND CAPPED VIAS. FILLING SHALL BE NON-CONDUCTIVE.
- FINISH:
 - SMOBC USING LPI BOTH SIDES, COLOR GREEN.
 - HARD GOLD FLASH FINISH OVERALL, WITH SELECT HARD GOLD PLATE.
 - SILKSCREEN LEGENDS SHALL BE WHITE NON-CONDUCTIVE EPOXY INK.
 - PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
 - SELECT HARD GOLD PLATE ON BOTH SIDES FOR THESE AREAS THAT ARE CLEARED OF SOLDERMASK, 2 PLACES EACH SIDE. THIS PLATING SHALL HAVE MINIMUM 30 MICROINCHES GOLD PER MIL-G-45204, TYPE II, CLASS I, GRADE C, OVER 200 MICROINCHES LOW STRESS NICKEL PER QQ-N-290, CLASS 2.
- FABRICATOR SHALL NOT ADD LOGO OR DATE CODE TO ARTWORK.
- BOARDS SHALL BE PANELIZED USING ROUTE AND RETAIN METHOD. THERE SHALL BE ONE RETAINING TAB ON EACH BOARD EDGE.
- ELECTRICAL TEST STAMPS SHALL BE ON SECONDARY SIDE ONLY.
- PCBS SHALL BE RoHS COMPLIANT.



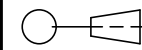
LINEAR TECHNOLOGY
DC2278A-X
LTC4281-UF
HIGH CURRENT HOT SWAP CONTROLLER
WITH I2C COMPATIBLE MONITORING AND EEPROM

SIZE	QTY	SYM	PLATED	TOL
10	234	+	YES	+/-0.003
120	4	X	NO	+/-0.003
65	19	□	YES	+/-0.003
35	48	◇	YES	+/-0.003
52	1	⊗	NO	+0.003/-0.000
16 x 25	28	⊗	YES	+/-0.003
39	1	⊕ ^A	YES	+0.003/-0.000
207	1	⊕ ^B	YES	+/-0.003
68	1	⊕ ^C	NO	+0.003/-0.000
20	845	⊕ ^D	YES	+/-0.003
12	93	⊕ ^E	YES	+/-0.003
50	4	⊕ ^F	YES	+/-0.003
266	2	⊕ ^G	NO	+/-0.005

FIG. 1
LAYER STRUCTURE



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES:
0.XX" = ±0.01"
0.XXX" = ±0.005"
INTERPRET DIM AND TOL
PER ASME Y14.5M-1994
THIRD ANGLE PROJECTION



APPROVALS

PCB DES. M.HAWKINS
APP ENG. BOB SMITH

SCALE = NONE



TITLE: FABRICATION DRAWING
HIGH CURRENT HOT SWAP CONTROLLER
WITH I2C COMPATIBLE MONITORING AND EEPROM

SIZE IC NO. LTC4281
N/A DEMO CIRCUIT 2278A
REV 02

SHT 1 OF 1